Product Information

Adhesives

Dow Corning® 96-083 Silicone Adhesive

2-part, 10:1 mix, translucent adhesive with high tensile strength and low viscosity

FEATURES

- Good flowability
- 10:1 mix ratio
- Heat cure
- High tensile strength
- No added solvents

BENEFITS

- Rapid, versatile cure processing controlled by temperature
- Able to flow, fill or self-leveling after dispensing

POTENTIAL USES

- Fixing components
- Bonding to various substrates such as ceramics, plastics, glass and metals

APPLICATION METHODS

- Automated or manual needle dispense

TYPICAL PROPERTIES

Specification Writers: Please contact your local Dow Corning sales office or your Global Dow Corning Connection before writing specifications on this product.

Property	Unit	Value
Viscosity (Part A or Base)	cP	10600
	mPa-sec	10600
	Pa-sec	10.6
Viscosity (Part B or Catalyst)	cP	275
	mPa-sec	275
	Pa-sec	0.3
Viscosity (Mixed)	cP	9450
	mPa-sec	9450
	Pa-sec	9.4
Thixotropy	NA	1.8
Heat Cure Time @ 150ºC	minutes	30
Durometer Shore A	-	55
Unprimed Adhesion - Lap Shear to Aluminum	psi	850
	MPa	5.9
	N/cm2	588
Shelf Life at 25ºC	months	12

DESCRIPTION

Dow Corning one-part heat cure (addition-curing) adhesives are typically cured at 100°C (212°F) or higher. Their cure rate is rapidly accelerated with heat (see cure schedules in table) and an optimum cure schedule will balance processing performance and costs. For thicker sections or if voiding is observed the use of a 30-minute pre-cure at 70°C (158°F) or the use of an adhesive with low-void technology may reduce voids. Addition-cure silicones are formulated with all necessary ingredients for cure and there are no by-products generated during the cure process. Deep-section or confined cures are possible as cure reactions progress evenly throughout the material. These adhesives generally have long working times so users can enjoy the greatest manufacturing flexibility and reduce waste. Dow Corning silicone adhesives retain their original physical and electrical properties over a broad range of operating conditions which enhance the reliability of and service life of electronic devices. The stable chemistry and versatile processing options of these adhesives offer benefits for a variety of electronics needs from increasing component safety and reliability, reducing total cost or increasing the performance envelope of devices or modules.

MIXING AND DE-AIRING

Dow Corning silicone 1:1 adhesives are supplied in two parts that do not require lot matching. The 1:1 mix ratio, by weight or volume, simplifies the proportioning process. To ensure uniform distribution of filler, Parts A and B must each be thoroughly mixed prior to their combination in a 1:1 ratio. When thoroughly blended, the Part A and B liquid mixture should have a uniform appearance. The presence of light colored streaks or marbling indicates inadequate mixing and will result in incomplete cure. For fast-curing adhesives automated mix and dispense equipment should be utilized. In applications sensitive to air entrapment, de-airing with 28 to 30 inches Hg vacuum is required.

ADHESION

In general, increasing the cure temperature and/or cure time will improve the ultimate adhesion. Dow Corning silicone adhesives are specially formulated to provide unprimed adhesion to many reactive metals, ceramics and glass, as well as to selected laminates, resins and plastics. However, good adhesion cannot be expected on non-reactive metal substrates or non-reactive plastic surfaces such as Teflon®, polyethylene or polypropylene. Special surface treatments such as chemical etching or plasma treatment can sometimes provide a reactive surface and promote adhesion to these types of substrates. Dow Corning® brand Primers can be used to increase the chemical activity on difficult substrates. Poor adhesion may be experienced on plastic or rubber substrates that are highly plasticized, because the mobile plasticizers act as release agents. Small-scale laboratory evaluation of all substrates is recommended before production trials are made.

COMPATIBILITY

Certain materials, chemicals, curing agents and plasticizers can inhibit the cure of addition cure adhesives. Most notable of these include: Organotin and other organometallic compounds, Silicone rubber containing organotin catalyst, Sulfur, polysulfides, polysulfones or other sulfur containing materials, unsaturated hydrocarbon plasitcizers, and some solder flux residues. If a substrate or material is questionable with respect to potentially causing inhibition of cure, it is recommended that a small scale compatibility test be run to ascertain suitability in a given application. The presence of liquid or uncured product at the interface between the questionable substrate and the cured gel indicates incompatibility and inhibition of cure.

PREPARING SURFACES

All surfaces should be thoroughly cleaned and/or degreased with Dow Corning® brand OS Fluids, naphtha, mineral spirits, methyl ethyl ketone (MEK) or other suitable solvent. Solvents such as acetone or isopropyl alcohol (IPA) do not tend to remove oils well, and any oils remaining on the surface may interfere with adhesion. Light surface abrasion is recommended whenever possible, because it promotes good cleaning and increases the surface area for bonding. A final surface wipe with acetone or IPA is also useful. Some cleaning techniques may provide better results than others; users should determine the best techniques for their particular applications.

SUBSTRATE TESTING

Due to the wide variety of substrate types and differences in substrate surface conditions, general statements on adhesion and bond strength are impossible. To ensure maximum bond strength on a particular substrate, 100 percent cohesive failure of the adhesive in a lap shear or similar adhesive strength test is desired. This ensures compatibility of the adhesive with the substrate being considered. Also, this test can be used to determine minimum cure time or can detect the presence of surface contaminants such as mold release agents, oils, greases and oxide films.

USEFUL TEMPERATURE RANGES

For most uses, silicone elastomers should be operational over a temperature range of -45 to 200°C (-49 to 392°F) for long periods of time. However, at both the low- and high temperature ends of the spectrum, behavior of the materials and performance in particular applications can become more complex and require additional considerations. For low-temperature performance, thermal cycling to conditions such as -55°C (-67°F) may be possible, but performance should be verified for your parts or assemblies. Factors that may influence performance are configuration and stress sensitivity of components, cooling rates and hold times, and prior temperature history. At the high-temperature end, the durability of the cured silicone elastomer is time and temperature dependent. As expected, the higher the temperature, the shorter the time the material will remain useable.

SOLVENT EXPOSURE

When liquid or vapor solvent or fuel exposure can occur in an application, the silicone adhesive discussed in this brochure is intended only to survive splash or intermittent exposures. It is not suited for continuous solvent or fuel exposure. Testing should be done to confirm performance of the adhesives under these conditions.

PACKAGING

In general, Dow Corning adhesives/sealants are supplied in nominal 0.45-, 3.6-, 18- and 200-kg (1-, 8-, 40- and 440-lb) containers, net weight. Not all products may be available in all packages and some additional packages, such as a bladder packs or tubes, may be available for certain package sizes.

STORAGE AND SHELF LIFE

Shelf life is indicated by the “Use Before” date found on the product label.

HEALTH AND ENVIRONMENTAL INFORMATION

To support customers in their product safety needs, Dow Corning has an extensive Product Stewardship organization and a team of Product Safety and Regulatory Compliance (PS&RC) specialists available in each area. For further information, please see our website, www.dowcorning.com, or consult your local Dow Corning representative.

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These products are neither tested nor represented as suitable for medical or pharmaceutical uses.

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